

PSMA Semiconductor Committee

Meeting Date: Friday, October 14th

Attendees: Joe Engle, Joe Horzepa, Tim McDonald, Ritu Sodhi

Discussion:

I. Industry Session at APEC 2017 (Ritu Sodhi)

- From the 5 SiC abstracts received for presentations, we had to select 2. Based on the inputs from some of the committee members, the two papers selected are from Wolfspeed and GeneSiC. The others will be requested to submit their papers directly to APEC.
- We also have confirmation from David Jauregui (TI) to present a paper on Silicon.
- The only open slot right now is the one for packaging as we haven't received a confirmation from Infineon folks yet. I will contact Brian N. to see if he has any recommendation. or if any of you know of some expert in this area please let me know.
- We also discussed the order of the papers and this is what we have decided. Exact titles will be included later.

1. Standardization for wide bandgap devices - Stephanie Butler (TI)
2. Silicon - David Jauregui (TI)
3. LV GaN - Alex Lidow (EPC)
4. HV GaN - Dan Kinzer (Navitas)
5. SiC-1 - John Mookken (Wolfspeed)
6. SiC-2 - Ranbir Singh (GeneSiC)
7. Packaging - TBD

II. WiPDA (Joe Engle)

- Exhibits are not selling too well this time, only two so far
- But there are several table tops being used by general workshop sponsors
- No further update. The lack of interest may also be because of the location?

III. Standardization Efforts (Tim McDonald)

- Work is continuing with the first milestone at WiPDA.
- There will be a meeting on Sunday before the workshop, where each sub-team has to give an update on their specific activities and also how they plan to build the relationship between each other. E.g. if there are specific reliability tests being recommended by the reliability team, then the test team needs to come up with test solutions for that, etc.

IV. Technology Roadmap Development (Tim McDonald)

- Continuing to get inputs from people in various areas
- The semiconductor part is pretty much covered
- Received one input for passives (Inductors), none on capacitors yet
- Also looking for inputs on packaging
- Work is delayed a bit, now planning to compile everything and send out for review by end of November.

Actions:

- Check with Brian N. if he has any recommendation for a packaging expert for the Industry Session --> **Ritu**
- Send any comments / suggestions you may have regarding the Industry Session paper sequence to Ritu asap --> **All committee members**
- Communicate our decision to the remaining SiC paper presenters so they can submit the abstract to general APEC --> **Ritu**
- Send the contact information for the professor at Georgia Tech to Ritu --> **Joe Engle**

Next Meeting: Friday, November 11th, 10AM Central

Thank you all!

Regards,
-Ritu.